

Description

The QSB363 is a silicon phototransistor encapsulated in a black infrared transparent T-3/4 package.

Features

- NPN Silicon Phototransistor
- T 40 to +85







T-3/4 2.50 x 2.00 CASES 100CB

T-3/4 2.50 x 2.00 CASES 100EH





T-3/4 2.50 x 2.00 CASES 100EJ

T-3/4 2.50 x 2.00 CASES 100EK

ORDERING INFORMATION

Device	Package	Shipping [†]
QSB363	T–3/4 2.50 x 2.00 100CB (Pb-Free, Halide Free)	1000 / Bulk Bag
QSB363GR	T–3/4 2.50 x 2.00 100EH (Pb-Free, Halide Free)	1000 / Tape & Reel
QSB363YR	T–3/4 2.50 x 2.00 100EJ (Pb-Free, Halide Free)	1000 / Tape & Reel
QSB363ZR	T–3/4 2.50 x 2.00 100EK (Pb-Free, Halide Free)	1000 / Tape & Reel

⁺For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, <u>BRD8011/D</u>.

°C Soldering Temperature (Iron) T_{SOL-I} °C 260 (Notes 1, 2) °C Soldering Temperature (Flow) T_{SOL-F} 260 (Notes 1, 2) Collector-Emitter Voltage 30 V V_{CEO} V VECO Emitter-Collector Voltage 5 75 Power Dissipation (Note 3) mW P_{C}

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. RMA flux is recommended.

- 2. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 3. Derate power dissipation linearly 1.08 mW/°C above 25°C.

QSB363

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Р	Peak Sensitivity Wavelength		-	940	-	nm
Θ	Reception Angle		-	±12		0
I _{CEO}	Collector Dark Current	V_{CE} = 20 V, E_e = 0 mW/cm ²	-	-	100	nA
BV _{CEO}	Collector–Emitter Breakdown Voltage	$I_{C} = 100$ A, $E_{e} = 0$ mW/cm ²	30	-	-	V
BV _{ECO}	Emitter–Collector Breakdown Voltage	$I_{E} = 100$ A, $E_{e} = 0$ mW/cm ²	5	-	-	V
I _{C(ON)}	On-State Collector Current	V _{CE}	-	-	-	-

QSB363

TYPICAL PERFORMANCE CHARACTERISTICS

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T 3/4 2.50x2.00 CASE 100CB ISSUE A

DATE 14 SEP 2023

NDTES:

- 1. CONTROLLING DIMENSIONS: MILLIMETERS
- 2. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- 3. 2MM DETECTOR



	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
A				
	1.30	1.40	1.50	
A3	1.30	1.40	1.50	
A4		0.60 REF	-	
b	-	0.55	0.65	
b1	0.35	0.45	0.55	
С	0.10	0.15	0.25	
	2.30		2.70	
E	1.80	2.00	2.20	
	7.00			
øD	1.70	1.90	2.10	





T-3/4 2.50x2.00 CASE 100EH ISSUE O

DATE 14 SEP 2023





RECOMMENDED MOUNTING FOOTPRINT* *FOR ADDITIONAL INFORMATION ON OUR P6-FREE STP

- 2. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- 3. 2MM YOKE DETECTOR.

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).650	0.750	0.850	
A5	0.550	0.650	0.750	
b	0.450	0.550	0.650	
ы1	0.350	0.450	0.550	
с	0.100	0.150	0.200	
D	2.300	2.500	2.700	
D1	1.200	1.400	1.600	
D2	0.900	1.100	1.300	
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BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT* *FOR ADDITIONAL INFORMATION ON OUR P6-FREE STRATEGY AND SOLDERING DETAILS



T-3/4 2.50x2.00 CASE 100EK ISSUE O

DATE 14 SEP 2023

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